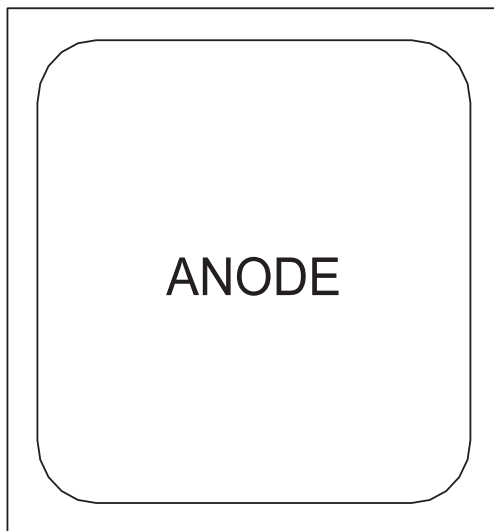


**PROCESS DETAILS**

Process	GLASS PASSIVATED MESA
Die Size	50 x 50 MILS
Die Thickness	9.5 MILS
Anode Bonding Pad Area	34 x 34 MILS
Top Side Metalization	Au - 5,000Å
Back Side Metalization	Au - 2,000Å

**GEOMETRY**



BACKSIDE CATHODE

R0

**GROSS DIE PER 4 INCH WAFER**

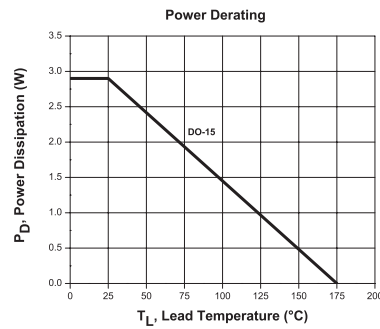
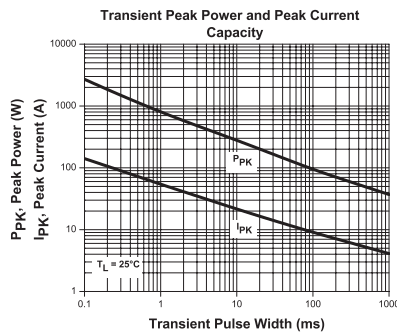
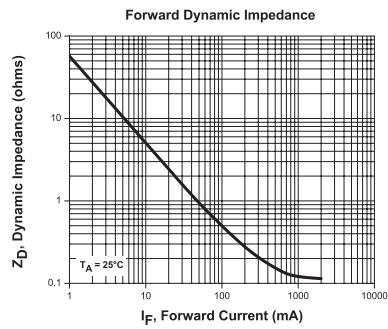
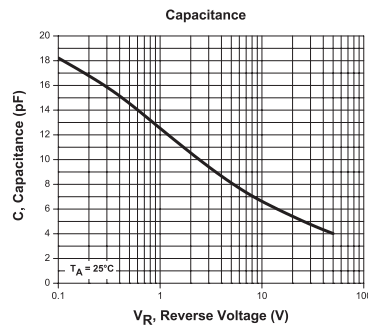
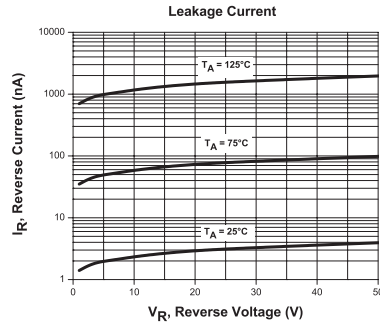
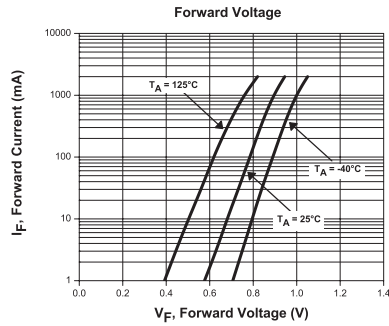
4,520

**PRINCIPAL DEVICE TYPES**

1N3611 thru 1N3614  
1N4001 thru 1N4007  
1N4245 thru 1N4249  
1N5059 thru 1N5062  
1N5391 thru 1N5399  
1N5614 thru 1N5622  
CMR1-02 Series  
CMR1-02M Series

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R3 (24-August 2006)



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